

Docket No.: 67161-144

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
	:	
Yasuhisa FUJII, et al.	:	Confirmation Number:
	:	
Serial No.:	:	Group Art Unit:
	:	
Filed: February 27, 2004	:	Examiner: Unknown
	:	
For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME		

**INFORMATION DISCLOSURE STATEMENT**

Mail Stop IDS  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

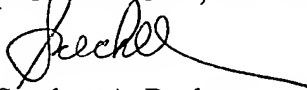
The relevance of the article "Stress-Induced Voiding Under Vias Connected To Wide Cu Metal Leads" is discussed in the present specification.

**Serial No.:**

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

MCDERMOTT, WILL & EMERY



Stephen A. Becker

Registration No. 26,527

600 13<sup>th</sup> Street, N.W.  
Washington, DC 20005-3096  
(202) 756-8000 SAB:tlb  
Facsimile: (202) 756-8087  
**Date: February 27, 2004**

INFORMATION DISCLOSURE CITATION IN AN APPLICATION				ATTY. DOCKET NO. <b>67161-144</b>		SERIAL NO.	
(PTO-1449)				APPLICANT <b>Yasuhisa FUJII, et al.</b>			
				FILING DATE <b>February 27, 2004</b>		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	CITE NO.	Document Number Number-Kind Code <sub>2</sub> ( <i>if known</i> )		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
		US					
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	CITE NO.	Foreign Patent Document Country Codes -Number 4 -Kind Codes ( <i>if known</i> )	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines Where Relevant Figures Appear	Translation	
						Yes	No
		JP 10-74762	03/17/1998	ULVAC JAPAN LTD		(Japan w/English Abstract)	
		JP P2000-306996A	11/02/2000	NEC CORP		(Japan w/English Abstract)	
		JP 11-340227	12/10/1999	FUJITSU LTD		(Japan w/English Abstract)	
		JP 11-102909	04/13/1999	SONY CORP		(Japan w/English Abstract)	
		JP P2000-269334A	09/29/2000	KOBE STEEL LTD		(Japan w/English Abstract)	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
EXAMINER'S INITIALS	CITE NO.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.					
		"Stress-Induced Voiding Under Vias Connected To Wide Cu Metal Leads", by E.T. Ogawa et al., IEEE 02CH37320 40th Annual International Reliability Physics Symposium, Dallas, Texas, 2002, pp. 312-321					
EXAMINER				DATE CONSIDERED			

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

1 Applicant's unique citation designation number (optional). 2 Applicant is to place a check mark here if English language Translation is attached.